NSBA114EDXV6T1, NSBA114EDXV6T5 SERIES

Dual Bias Resistor Transistors

PNP Silicon Surface Mount Transistors with Monolithic Bias Resistor Network

The BRT (Bias Resistor Transistor) contains a single transistor with a monolithic bias network consisting of two resistors; a series base resistor and a base−emitter resistor. These digital transistors are designed to replace a single device and its external resistor bias network. The BRT eliminates these individual components by integrating them into a single device. In the NSBA114EDXV6T1 series, two BRT devices are housed in the SOT−563 package which is ideal for low−power surface mount applications where board space is at a premium.

Features

- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- These are Pb−Free Devices
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable

MAXIMUM RATINGS

(T_A = 25°C unless otherwise noted, common for Q_1 and Q_2)

Rating	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	−50	Vdc
Collector-Emitter Voltage	V_{CEO}	−50	Vdc
Collector Current	I_C	−100	mAdc

THERMAL CHARACTERISTICS

Characteristic (One Junction Heated)	Symbol	Max	Unit
Total Device Dissipation @ T_A = 25°C Derate above 25°C (Note 1)	P_D	357 2.9	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	350	°C/W
Characteristic (Both Junctions Heated)	**Symbol**	**Max**	**Unit**
Total Device Dissipation @ T_A = 25°C Derate above 25°C (Note 1)	P_D	500 4.0	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	250	°C/W
Junction and Storage Temperature Range	T_J, T_{stg}	−55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR−4 @ Minimum Pad

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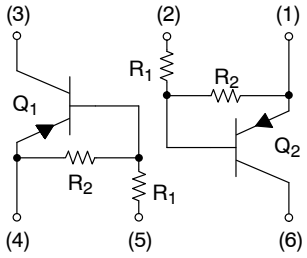
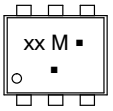


SOT−563
CASE 463A
STYLE 1

MARKING DIAGRAM



xx = Device Code
(Refer to page 2)
M = Date Code
▪ = Pb−Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
NSBA1xxxDXV6T1	SOT−563	4000/Tape & Reel
NSBA1xxxDXV6T1G	SOT−563	4000/Tape & Reel
NSVBA1xxxDXV6T1G	SOT−563	4000/Tape & Reel
NSBA1xxxDXV6T5	SOT−563	8000/Tape & Reel
NSBA1xxxDXV6T5G	SOT−563	8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

DEVICE MARKING INFORMATION

See specific marking information in the device marking table on page 2 of this data sheet.

DEVICE MARKING AND RESISTOR VALUES

Device*	Package	Marking	R1 (kΩ)	R2 (kΩ)
NSBA114EDXV6T1 / T5	SOT−563	0A	10	10
NSBA124EDXV6T1 / T5	SOT−563	0B	22	22
NSBA144EDXV6T1 / T5	SOT−563	0C	47	47
NSBA114YDXV6T1 / T5 / NSVBA114YDXV6T1G	SOT−563	0D	10	47
NSBA114TDXV6T1 / T5 (Note 2)	SOT−563	0E	10	∞
NSBA143TDXV6T1 / T5 (Note 2)	SOT−563	0F	4.7	∞
NSBA113EDXV6T1 / T5 (Note 2)	SOT−563	0G	1.0	1.0
NSBA123EDXV6T1 / T5 (Note 2)	SOT−563	0H	2.2	2.2
NSBA143EDXV6T1 / T5 (Note 2)	SOT−563	0J	4.7	4.7
NSBA143ZDXV6T1 / T5 (Note 2)	SOT−563	0K	4.7	47
NSBA124XDXV6T1 / T5 (Note 2)	SOT−563	0L	22	47
NSBA123JDXV6T1 / T5 (Note 2)	SOT−563	0M	2.2	47
NSBA115EDXV6T1 / T5 (Note 2)	SOT−563	0N	100	100
NSBA144WDXV6T1 (Note 2)	SOT−563	0P	47	22

*The “G” suffix indicates Pb−Free package available. Refer to Ordering Information Table on page 1.
2. New resistor combinations. Updated curves to follow in subsequent data sheets.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted, common for Q_1 and Q_2)

Characteristic		Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Collector-Base Cutoff Current (V_{CB} = −50 V, I_E = 0)		I_{CBO}	−	−	−100	nAdc
Collector-Emitter Cutoff Current (V_{CE} = −50 V, I_B = 0)		I_{CEO}	−	−	−500	nAdc
Emitter-Base Cutoff Current (V_{EB} = −6.0 V, I_C = 0)	NSBA114EDXV6T1	I_{EBO}	−	−	−0.5	mAdc
	NSBA124EDXV6T1		−	−	−0.2	
	NSBA144EDXV6T1		−	−	−0.1	
	NSBA114YDXV6T1 / NSVBA114YDXV6T1G		−	−	−0.2	
	NSBA114TDXV6T1		−	−	−0.9	
	NSBA143TDXV6T1		−	−	−1.9	
	NSBA113EDXV6T1		−	−	−4.3	
	NSBA123EDXV6T1		−	−	−2.3	
	NSBA143EDXV6T1		−	−	−1.5	
	NSBA143ZDXV6T1		−	−	−0.18	
	NSBA124XDXV6T1		−	−	−0.13	
	NSBA123JDXV6T1		−	−	−0.2	
	NSBA115EDXV6T1		−	−	−0.05	
	NSBA144WDXV6T1		−	−	−0.13	
Collector-Base Breakdown Voltage (I_C = −10 μA, I_E = 0)		$V_{(BR)CBO}$	−50	−	−	Vdc
Collector-Emitter Breakdown Voltage (Note 3) (I_C = −2.0 mA, I_B = 0)		$V_{(BR)CEO}$	−50	−	−	Vdc
ON CHARACTERISTICS (Note 3)						
Collector-Emitter Saturation Voltage (I_C = −10 mA, I_E = −0.3 mA) (I_C = −10 mA, I_B = −5 mA) NSBA113EDXV6T1/NSBA123EDXV6T1 (I_C = −10 mA, I_B = −1 mA) NSBA114TDXV6T1/NSBA143TDXV6T1 NSBA143EDXV6T1/NSBA143ZDXV6T1/NSBA124XDXV6T1		$V_{CE(sat)}$	−	−	−0.25	Vdc

3. Pulse Test: Pulse Width < 300 μs, Duty Cycle < 2.0%

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted, common for Q_1 and Q_2) (continued)

Characteristic		Symbol	Min	Typ	Max	Unit
ON CHARACTERISTICS (Note 3) (continued)						
DC Current Gain	NSBA114EDXV6T1	h_{FE}	35	60	–	
(V_{CE} = −10 V, I_C = −5.0 mA)	NSBA124EDXV6T1		60	100	–	
	NSBA144EDXV6T1		80	140	–	
	NSBA114YDXV6T1 / NSVBA114YDXV6T1G		80	140	–	
	NSBA114TDXV6T1		160	250	–	
	NSBA143TDXV6T1		160	250	–	
	NSBA113EDXV6T1		3.0	5.0	–	
	NSBA123EDXV6T1		8.0	15	–	
	NSBA143EDXV6T1		15	27	–	
	NSBA143ZDXV6T1		80	140	–	
	NSBA124XDXV6T1		80	130	–	
	NSBA123JDXV6T1		80	140	–	
	NSBA115EDXV6T1		80	130	–	
	NSBA144WDXV6T1		80	140	–	
Output Voltage (on)		V_{OL}				Vdc
(V_{CC} = −5.0 V, V_B = −2.5 V, R_L = 1.0 kΩ)	NSBA114EDXV6T1		–	–	−0.2	
	NSBA124EDXV6T1		–	–	−0.2	
	NSBA114YDXV6T1 / NSVBA114YDXV6T1G		–	–	−0.2	
	NSBA114TDXV6T1		–	–	−0.2	
	NSBA143TDXV6T1		–	–	−0.2	
	NSBA113EDXV6T1		–	–	−0.2	
	NSBA123EDXV6T1		–	–	−0.2	
	NSBA143EDXV6T1		–	–	−0.2	
	NSBA143ZDXV6T1		–	–	−0.2	
	NSBA124XDXV6T1		–	–	−0.2	
	NSBA123JDXV6T1		–	–	−0.2	
(V_{CC} = −5.0 V, V_B = −3.5 V, R_L = 1.0 kΩ)	NSBA144EDXV6T1		–	–	−0.2	
(V_{CC} = −5.0 V, V_B = −5.5 V, R_L = 1.0 kΩ)	NSBA115EDXV6T1		–	–	−0.2	
(V_{CC} = −5.0 V, V_B = −4.0 V, R_L = 1.0 kΩ)	NSBA144WDXV6T1		–	–	−0.2	
Output Voltage (off) (V_{CC} = −5.0 V, V_B = −0.5 V, R_L = 1.0 kΩ)		V_{OH}	−4.9	–	–	Vdc
(V_{CC} = −5.0 V, V_B = −0.05 V, R_L = 1.0 kΩ)	NSBA113EDXV6T1					
(V_{CC} = −5.0 V, V_B = −0.25 V, R_L = 1.0 kΩ)	NSBA114TDXV6T1					
	NSBA143TDXV6T1					
	NSBA123EDXV6T1					
	NSBA143ZDXV6T1					
Input Resistor	NSBA114EDXV6T1	R_1	7.0	10	13	k Ω
	NSBA124EDXV6T1		15.4	22	28.6	
	NSBA144EDXV6T1		32.9	47	61.1	
	NSBA114YDXV6T1 / NSVBA114YDXV6T1G		7.0	10	13	
	NSBA114TDXV6T1		7.0	10	13	
	NSBA143TDXV6T1		3.3	4.7	6.1	
	NSBA113EDXV6T1		0.7	1.0	1.3	
	NSBA123EDXV6T1		1.5	2.2	2.9	
	NSBA143EDXV6T1		3.3	4.7	6.1	
	NSBA143ZDXV6T1		3.3	4.7	6.1	
	NSBA124XDXV6T1		15.4	22	28.6	
	NSBA123JDXV6T1		1.54	2.2	2.86	
	NSBA115EDXV6T1		70	100	130	
	NSBA144WDXV6T1		32.9	47	61.1	
Resistor Ratio	NSBA114EDXV6T1/NSBA124EDXV6T1/ NSBA144EDXV6T1/NSBA115EDXV6T1	R_1/R_2	0.8	1.0	1.2	
	NSBA114YDXV6T1/NSVBA114YDXV6T1G		0.17	0.21	0.25	
	NSBA114TDXV6T1/NSBA143TDXV6T1		–	–	–	
	NSBA113EDXV6T1/NSBA123EDXV6T1/NSBA143EDXV6T1		0.8	1.0	1.2	
	NSBA143ZDXV6T1		0.055	0.1	0.185	
	NSBA124XDXV6T1		0.38	0.47	0.56	
	NSBA123JDXV6T1		0.038	0.047	0.056	
	NSBA144WDXV6T1		1.7	2.1	2.6	

3. Pulse Test: Pulse Width < 300 μs, Duty Cycle < 2.0%

ALL NSBA114EDXV6T1 SERIES DEVICES

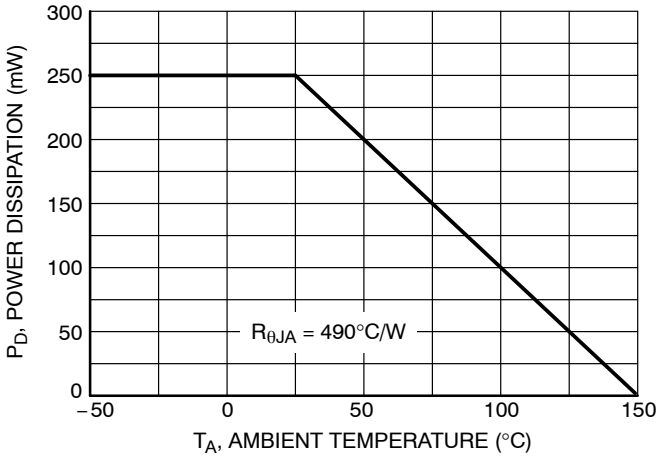


Figure 1. Derating Curve – ALL DEVICES

TYPICAL ELECTRICAL CHARACTERISTICS — NSBA114EDXV6T1

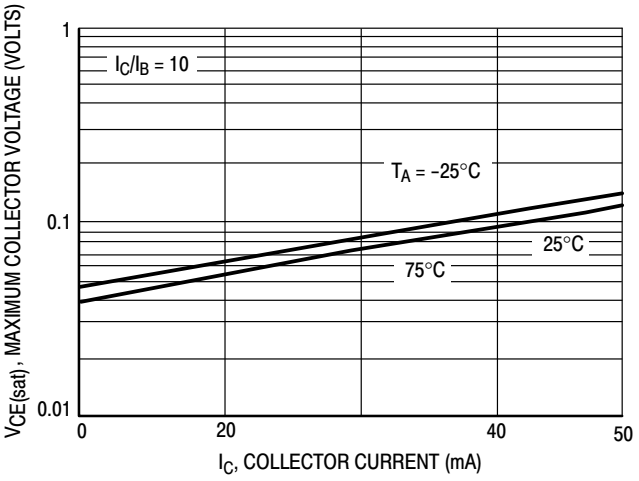


Figure 2. $V_{CE(sat)}$ versus I_C

TYPICAL ELECTRICAL CHARACTERISTICS — NSBA114EDXV6T1

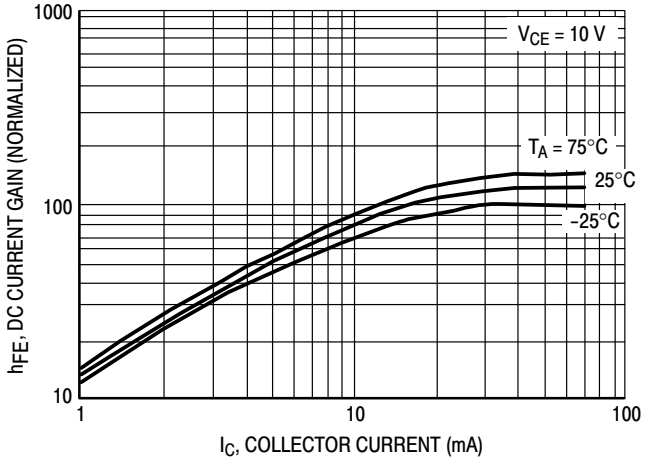


Figure 3. DC Current Gain

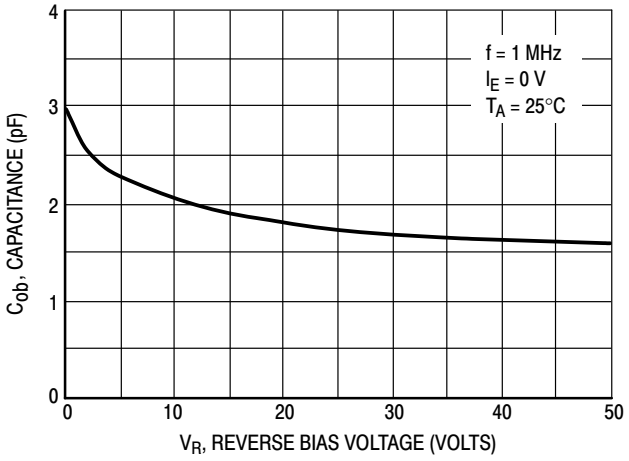


Figure 4. Output Capacitance

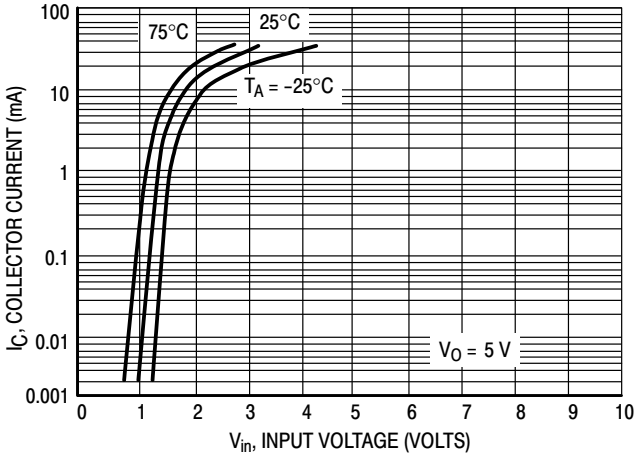


Figure 5. Output Current versus Input Voltage

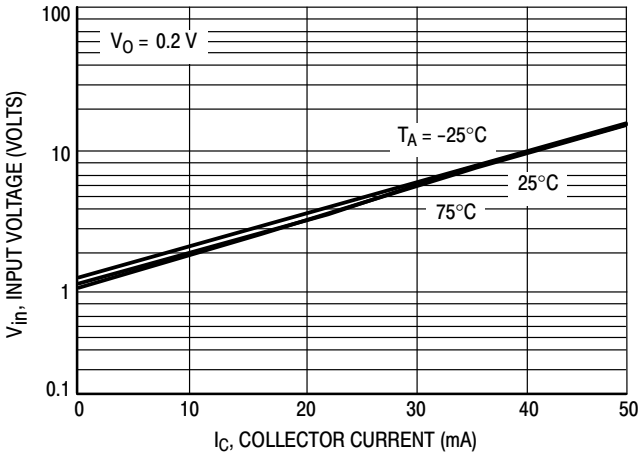


Figure 6. Input Voltage versus Output Current

TYPICAL ELECTRICAL CHARACTERISTICS — NSBA124EDXV6T1

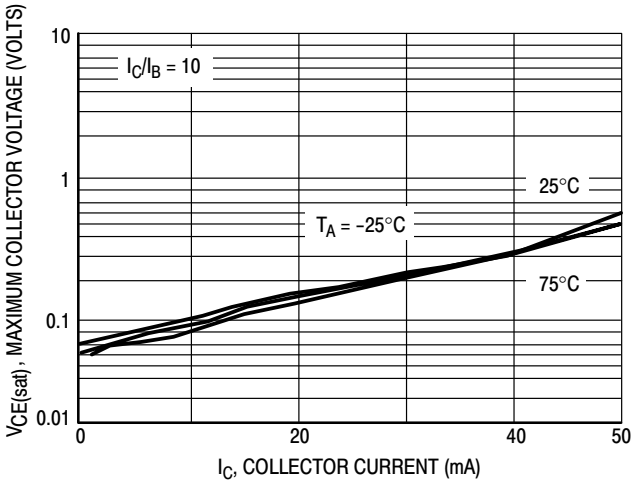


Figure 7. $V_{CE(sat)}$ versus I_C

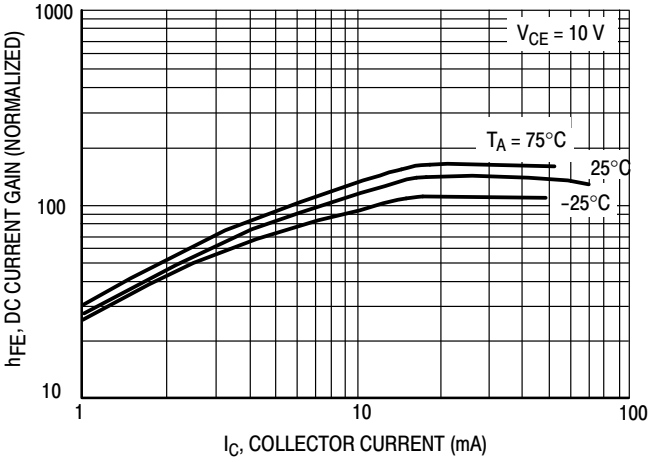


Figure 8. DC Current Gain

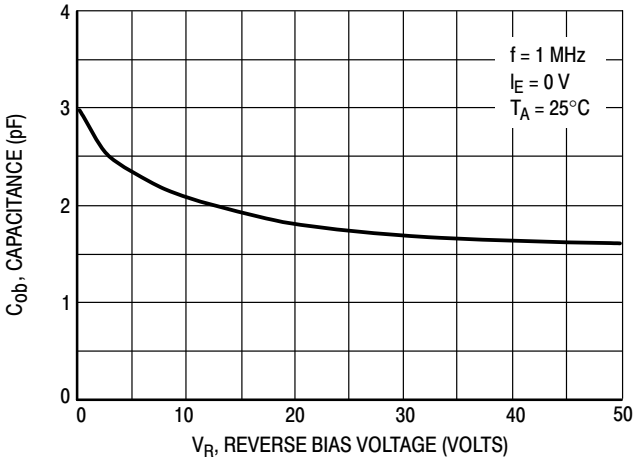


Figure 9. Output Capacitance

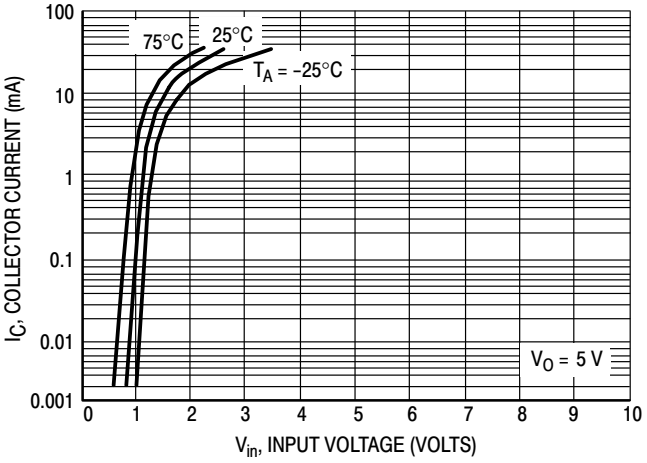


Figure 10. Output Current versus Input Voltage

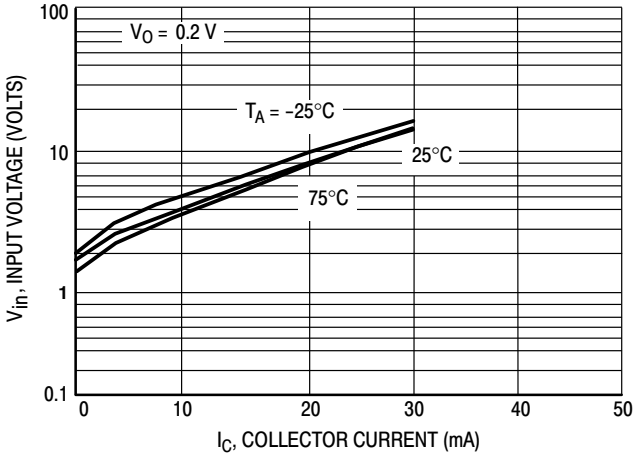


Figure 11. Input Voltage versus Output Current

TYPICAL ELECTRICAL CHARACTERISTICS — NSBA144EDXV6T1

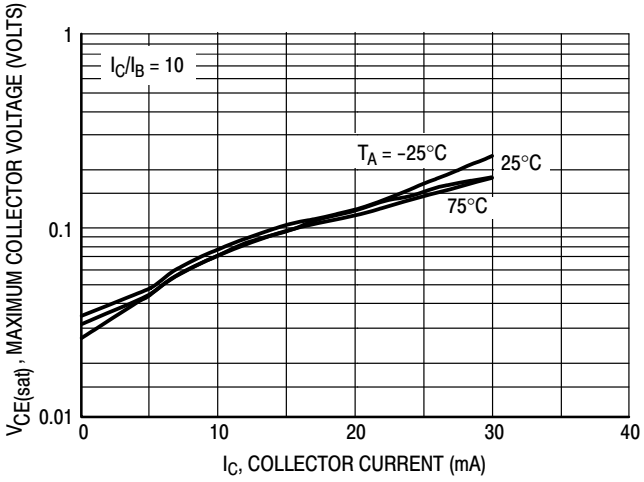


Figure 12. $V_{CE(sat)}$ versus I_C

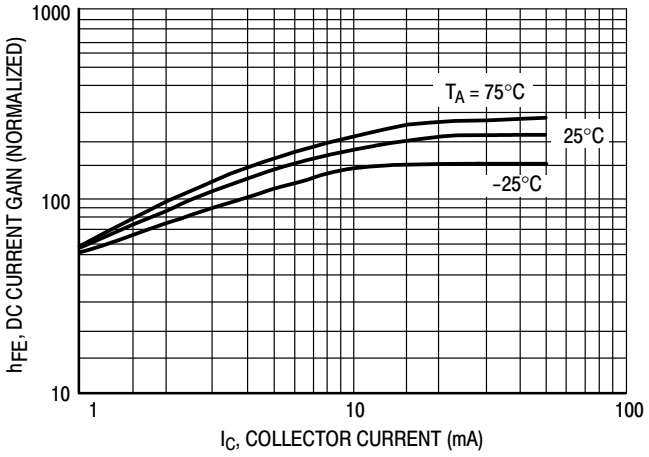


Figure 13. DC Current Gain

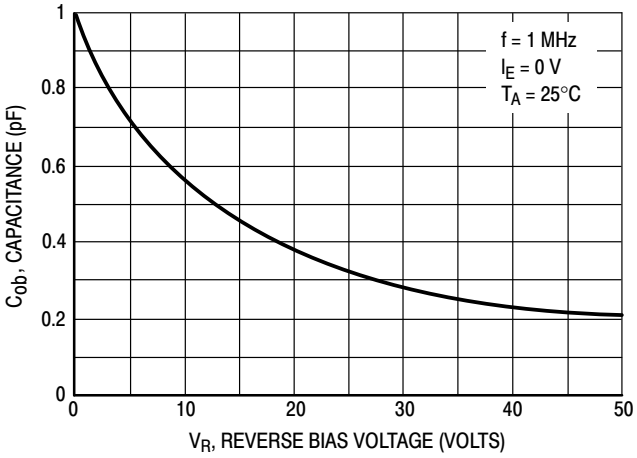


Figure 14. Output Capacitance

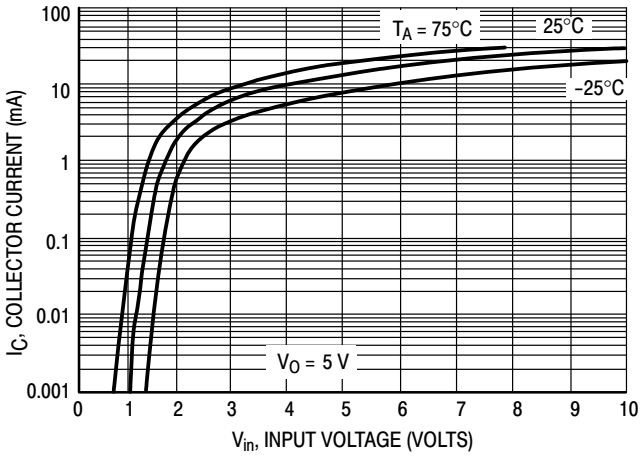


Figure 15. Output Current versus Input Voltage

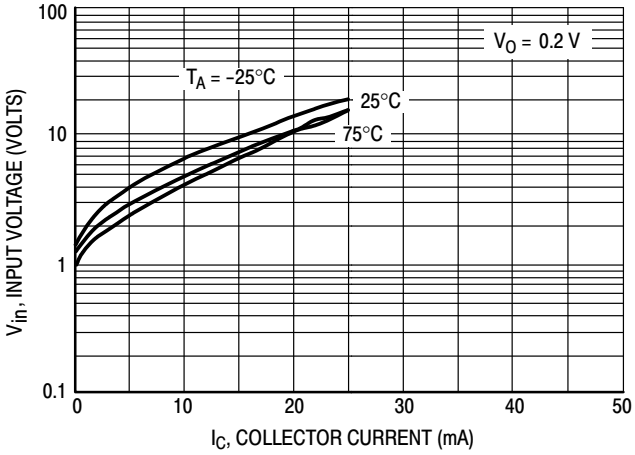


Figure 16. Input Voltage versus Output Current

TYPICAL ELECTRICAL CHARACTERISTICS — NSBA114YDXV6T1 / NSVBA114YDXV6T1G

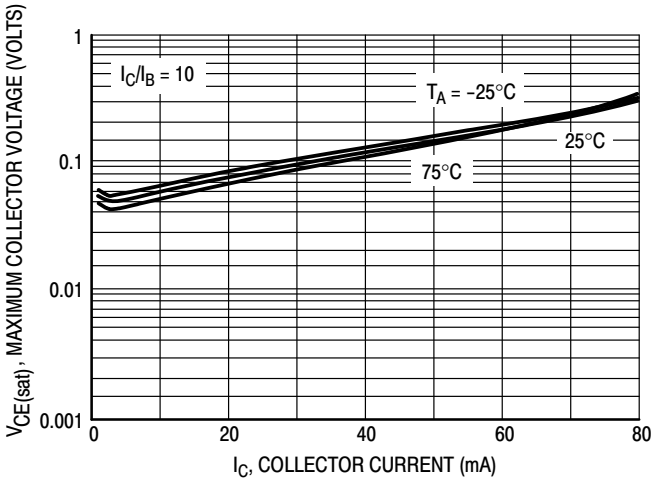


Figure 17. $V_{CE(sat)}$ versus I_C

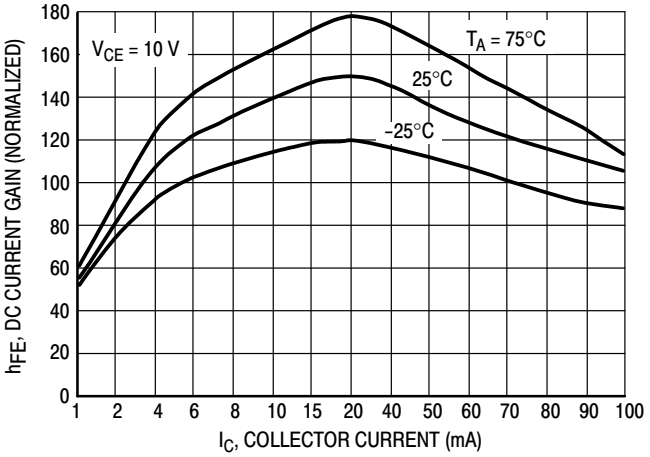


Figure 18. DC Current Gain

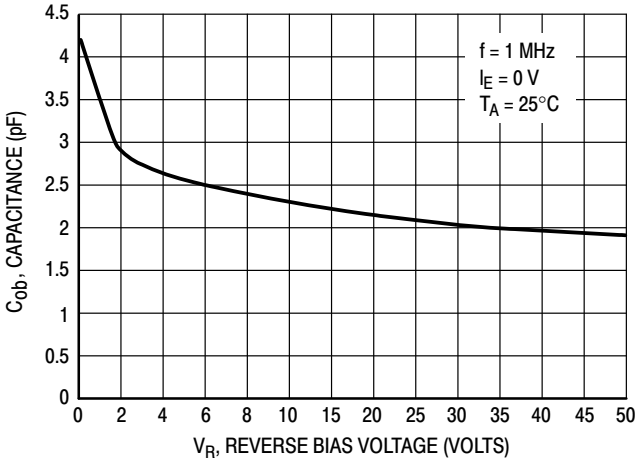


Figure 19. Output Capacitance

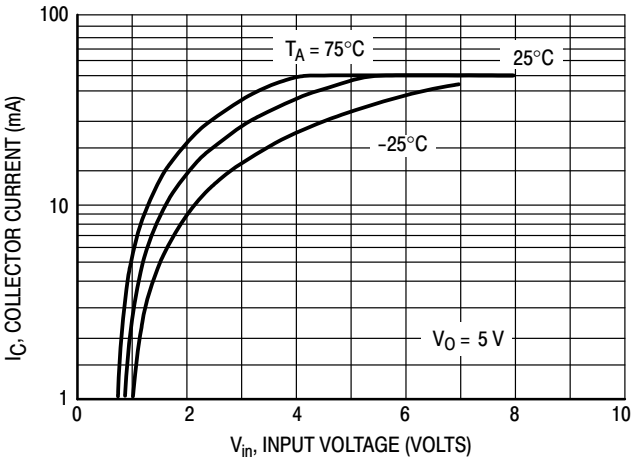


Figure 20. Output Current versus Input Voltage

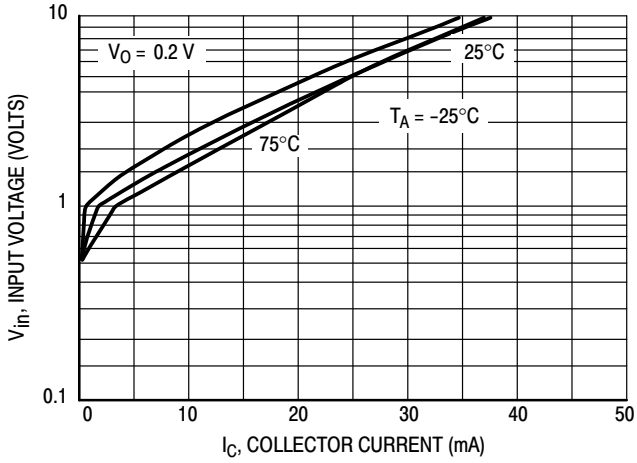


Figure 21. Input Voltage versus Output Current

TYPICAL ELECTRICAL CHARACTERISTICS — NSBA114TDXV6T1

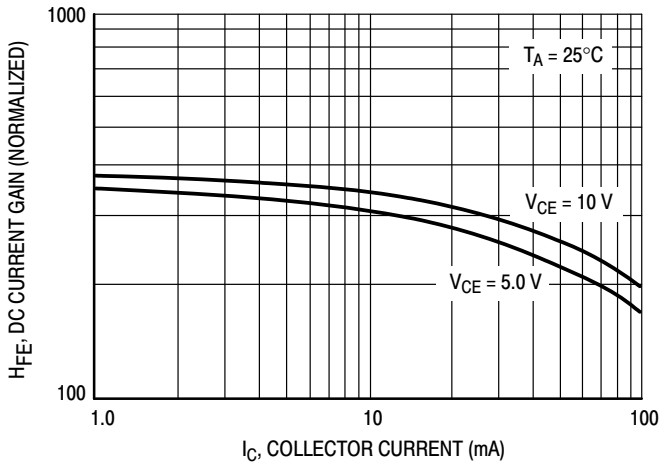


Figure 22. DC Current Gain

TYPICAL ELECTRICAL CHARACTERISTICS — NSBA143TDXV6T1

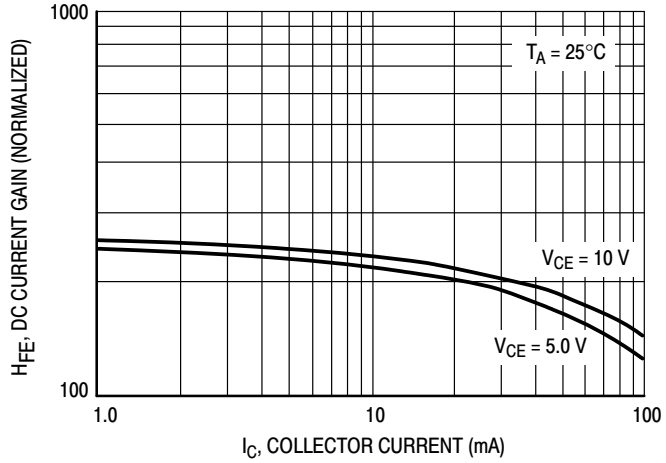


Figure 23. DC Current Gain

TYPICAL ELECTRICAL CHARACTERISTICS — NSBA115EDXV6T1

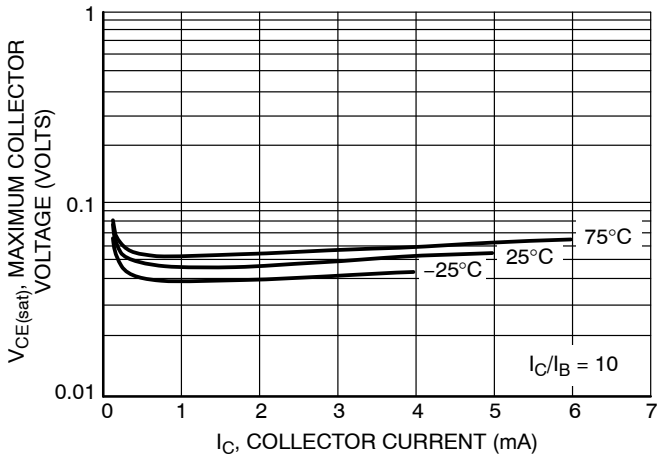


Figure 24. Maximum Collector Voltage versus Collector Current

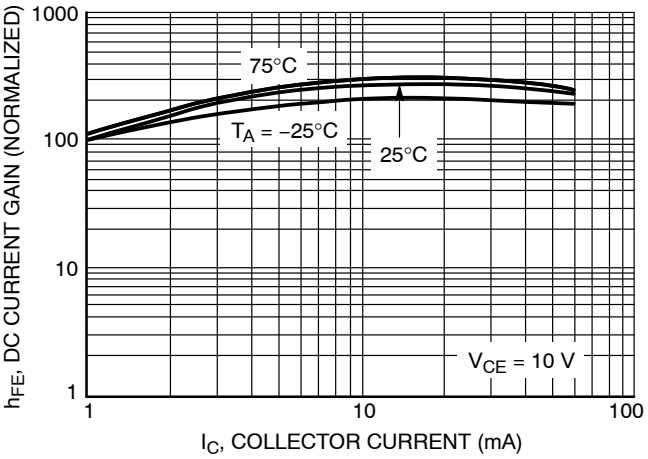


Figure 25. DC Current Gain

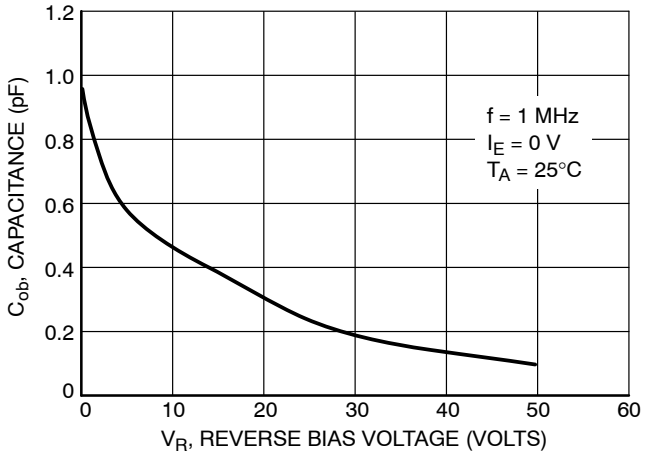


Figure 26. Output Capacitance

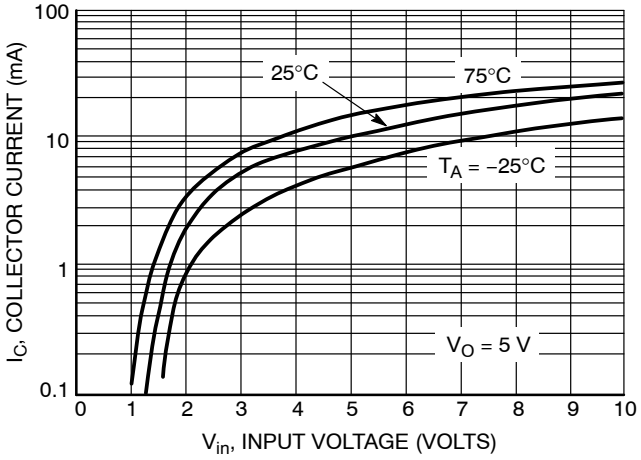


Figure 27. Output Current versus Input Voltage

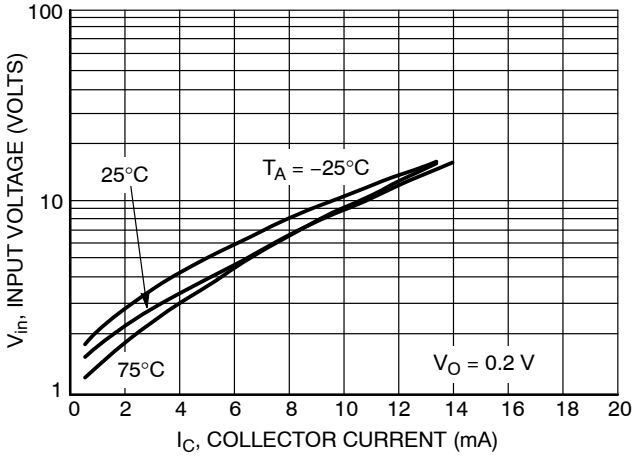


Figure 28. Input Voltage versus Output Current

TYPICAL ELECTRICAL CHARACTERISTICS — NSBA144WDXV6T1

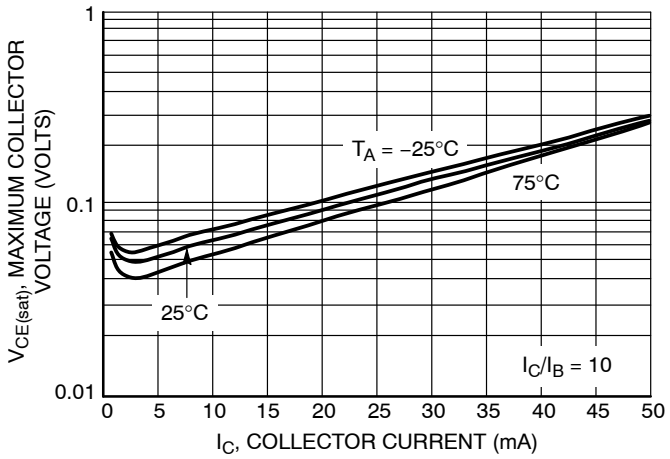


Figure 29. Maximum Collector Voltage versus Collector Current

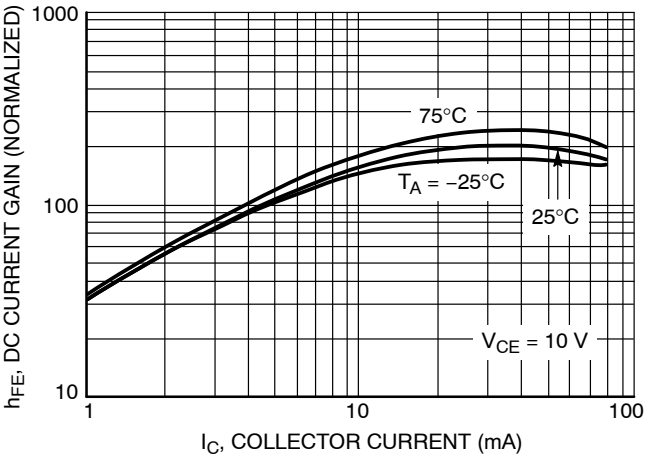


Figure 30. DC Current Gain

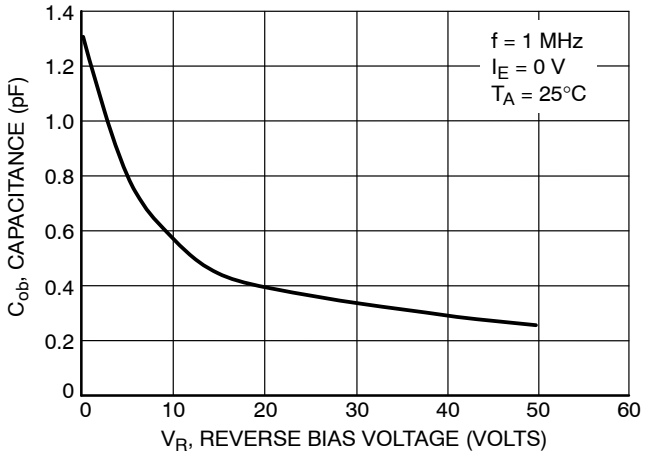


Figure 31. Output Capacitance

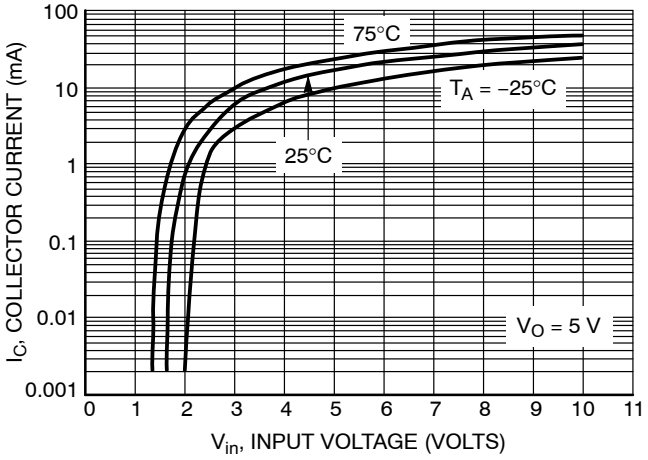


Figure 32. Output Current versus Input Voltage

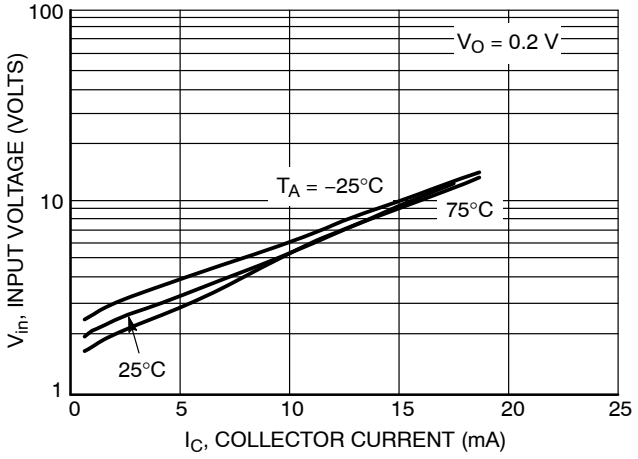
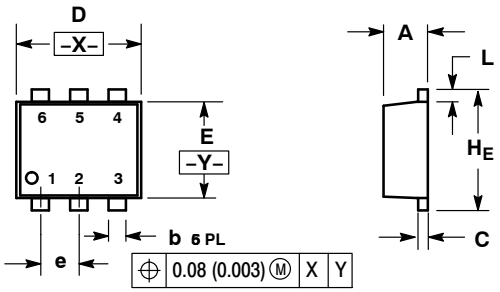


Figure 33. Input Voltage versus Output Current

PACKAGE DIMENSIONS

SOT−563, 6 LEAD
CASE 463A
ISSUE F

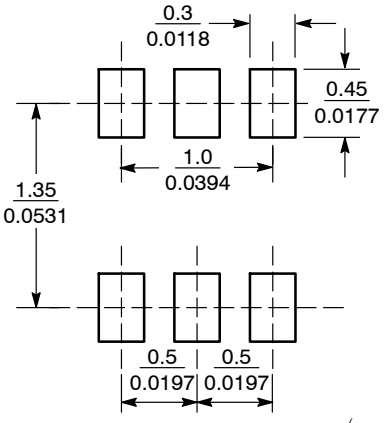


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.55	0.60	0.020	0.021	0.023
b	0.17	0.22	0.27	0.007	0.009	0.011
C	0.08	0.12	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.062	0.066
E	1.10	1.20	1.30	0.043	0.047	0.051
e	0.5 BSC			0.02 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
H_E	1.50	1.60	1.70	0.059	0.062	0.066

STYLE 1:
PIN 1. EMITTER 1
2. BASE 1
3. COLLECTOR 2
4. EMITTER 2
5. BASE 2
6. COLLECTOR 1

SOLDERING FOOTPRINT*



SCALE 20:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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- Поставка сложных, дефицитных, либо снятых с производства позиций;
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- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
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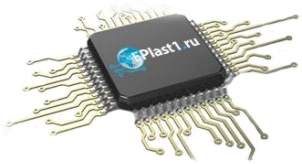
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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